



100V +175°C N-CHANNEL ENHANCEMENT MODE MOSFET PowerDI5060-8

Product Summary

BV _{DSS}	R _{DS(ON)} Max	I _D T _C = +25°C
400\/	$3m\Omega$ @ $V_{GS} = 10V$	166A
100V	$5m\Omega @ V_{GS} = 6V$	129A

Description and Applications

This MOSFET is designed to minimize the on-state resistance (RDS(ON)) yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- Engine Management Systems
- **Body Control Electronics**
- DC-DC Converters

Features

- Rated to +175°C Ideal for High Ambient Temperature **Environments**
- 100% Unclamped Inductive Switching (UIS) Test in Production -Ensures More Reliable and Robust End Application
- Low RDS(ON) Minimizes On State Losses
- Low Input Capacitance
- Fast Switching Speed
- Wettable Flank for Improved Optical Inspection
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please contact us or your local Diodes representative. https://www.diodes.com/quality/product-definitions/

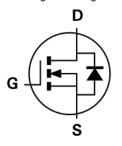
Mechanical Data

- Package: PowerDI®5060-8
- Package Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Finish Matte Tin Annealed over Copper Leadframe; Solderable per MIL-STD-202, Method 208@3
- Weight: 0.097 grams (Approximate)

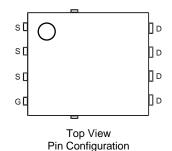


PowerDI5060-8 (SWP) (Type Q)

Top View **Bottom View**



Internal Schematic



Ordering Information (Note 4)

Part Number	Backago	Packing		
Part Number	Package	Qty.	Carrier	
DMTH10H003SPSW-13	PowerDI5060-8 (SWP) (Type Q)	2,500	Tape & Reel	

Notes:

- 1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information



D : I = Manufacturer's Marking H10H003SW = Product Type Marking Code YYWW = Date Code Marking YY = Last Two Digits of Year (ex: 21 = 2021) WW = Week Code (01 to 53)

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Maximum Ratings (@ $T_A = +25$ °C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Drain-Source Voltage		V _{DSS}	100	V
Gate-Source Voltage		Vgss	±20	V
Continuous Drain Current, V _{GS} = 10V (Note 6)	T _C = +25°C T _C = +100°C	lo	166 117	А
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)		I _{DM}	664	A
Maximum Continuous Body Diode Forward Current (Note 6)		Is	166	Α
Pulsed Body Diode Forward Current (10µs Pulse, Duty Cycle = 1%)		Ism	664	A
Avalanche Current, L = 3mH		las	20.2	A
Avalanche Energy, L = 3mH		E _{AS}	612	mJ

Thermal Characteristics

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 5)	$T_A = +25$ °C	PD	2.6	W
Thermal Resistance, Junction to Ambient (Note 5)		$R_{\theta JA}$	57	°C/W
Total Power Dissipation (Note 6) $T_C = +25^{\circ}C$		PD	167	W
Thermal Resistance, Junction to Case (Note 6)		R _θ JC	0.9	°C/W
Operating and Storage Temperature Range		TJ, TSTG	-55 to +175	°C

Electrical Characteristics (@TA = +25°C, unless otherwise specified.)

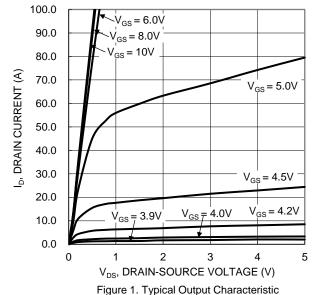
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)							
Drain-Source Breakdown Voltage	BV _{DSS}	100	_	_	V	$V_{GS} = 0V$, $I_D = 1mA$	
Zero Gate Voltage Drain Current	IDSS	_	_	1	μΑ	V _{DS} = 80V, V _{GS} = 0V	
Gate-Source Leakage	Igss	_	_	±100	nA	$V_{GS} = \pm 20V$, $V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7)							
Gate Threshold Voltage	Vgs(TH)	2	2.6	4	V	$V_{DS} = V_{GS}$, $I_D = 250\mu A$	
Static Drain-Source On-Resistance	Dagger		2.2	3	mΩ	V _{GS} = 10V, I _D = 30A	
Static Dialii-Source Off-Resistance	RDS(ON)		3.4	5	mΩ	$V_{GS} = 6V, I_D = 25A$	
Diode Forward Voltage	VsD		8.0	1.2	V	V _G S = 0V, I _S = 20A	
DYNAMIC CHARACTERISTICS (Note 8)	DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	Ciss	_	5542	_		V _{DS} = 50V, V _{GS} = 0V, f = 1MHz	
Output Capacitance	Coss	_	1681	_	pF		
Reverse Transfer Capacitance	Crss	_	34	_			
Gate Resistance	Rg	_	1.46	_	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$	
Total Gate Charge	Qg	_	85.0	_		V _{DS} = 50V, I _D = 30A, V _{GS} = 10V	
Gate-Source Charge	Qgs	_	21.0	_	nC		
Gate-Drain Charge	Qgd	_	19.7	_			
Turn-On Delay Time	t _{D(ON)}	_	16.0	_		$V_{DD} = 50V, V_{GS} = 10V,$ $I_{D} = 30A, R_{g} = 3\Omega$	
Turn-On Rise Time	t _R	_	23.2	_			
Turn-Off Delay Time	tD(OFF)	_	45.3	_	ns		
Turn-Off Fall Time	t _F	_	29.6	_			
Body Diode Reverse Recovery Time	t _{RR}	_	71.7	_	ns	I_ 200 di/dt 4000/	
Body Diode Reverse Recovery Charge	Q _{RR}		163.1	_	nC	I _F = 30A, di/dt = 100A/μs	

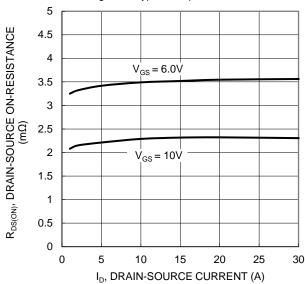
Notes: 5. Device mounted on FR-4 substrate PCB, 2oz copper, with thermal bias to bottom layer 1inch square copper plate.

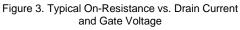
6. Thermal resistance from junction to soldering point (on the exposed drain pad).
7. Short duration pulse test used to minimize self-heating effect.
8. Guaranteed by design. Not subject to product testing.











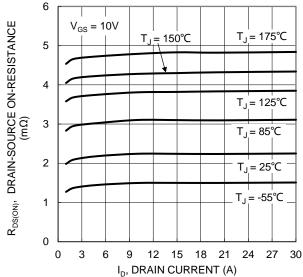
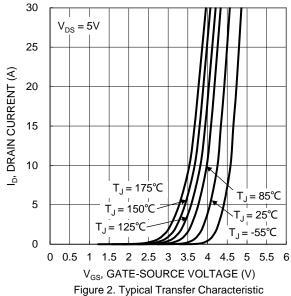


Figure 5. Typical On-Resistance vs. Drain Current and Junction Temperature



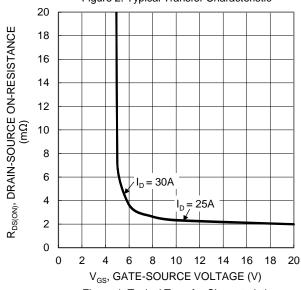


Figure 4. Typical Transfer Characteristic

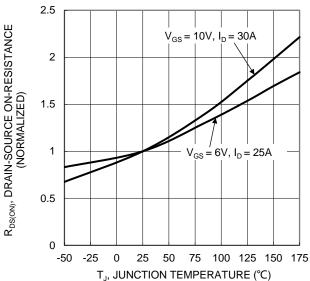


Figure 6. On-Resistance Variation with Junction
Temperature





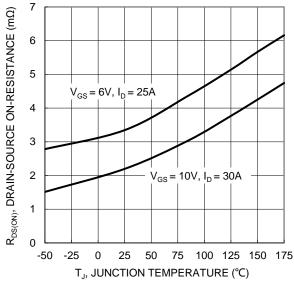


Figure 7. On-Resistance Variation with Junction Temperature

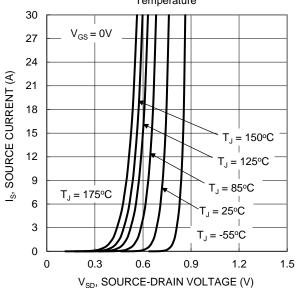


Figure 9. Diode Forward Voltage vs. Current

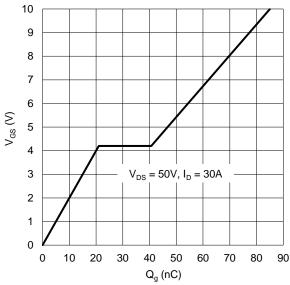


Figure 11. Gate Charge

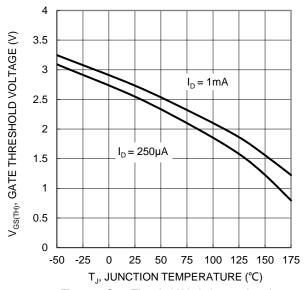


Figure 8. Gate Threshold Variation vs. Junction Temperature

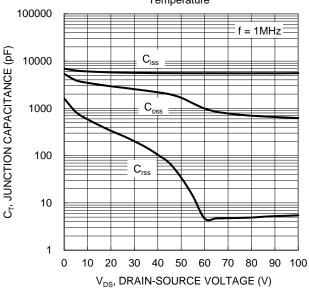
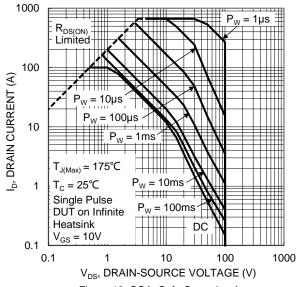


Figure 10. Typical Junction Capacitance





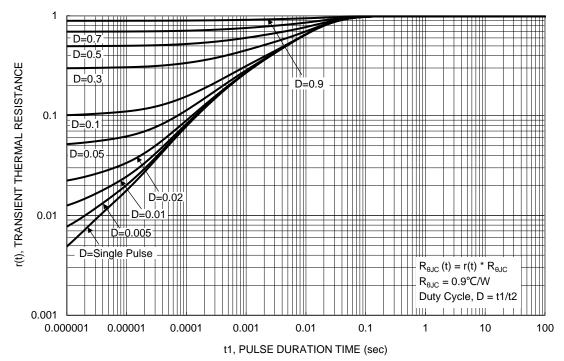


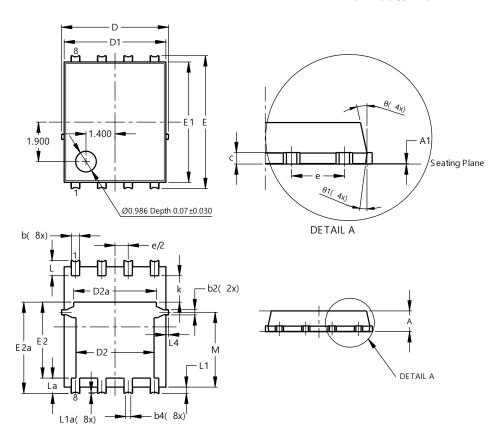
Figure 13. Transient Thermal Resistance



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

PowerDI5060-8 (SWP) (Type Q)

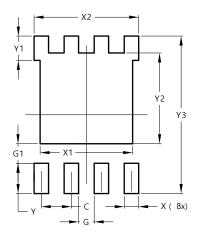


PowerDI5060-8 (SWP) (Type Q)					
Dim	Min Max		Тур		
Α	0.90	1.10	1.00		
A1	0	0.05	-		
b	0.30	0.50	0.41		
b2	0.20	0.35	0.25		
b4	C).25REF	=		
С	0.230	0.330	0.277		
D	5.15 BSC				
D1	4.70	5.10	4.90		
D2	3.56	3.96	3.76		
D2a	3.78	4.18	3.98		
Е	6	.40 BS0)		
E1	5.60	6.00	5.80		
E2	3.46	3.86	3.66		
E2a	4.195 4.595		4.395		
е	1	.27BSC)		
k	1.05				
L	0.635	0.835	0.735		
La	0.635	0.835	0.735		
L1	0.200	0.400	0.300		
L1a	0.050REF				
L4	0.025	0.225	0.125		
М	3.205	4.005	3.605		
θ	10°	12°	11°		
θ1	6°	8°	7°		
All Dimensions in mm					

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

PowerDI5060-8 (SWP) (Type Q)



Dimensions	Value (in mm)		
С	1.270		
G	0.660		
G1	0.820		
X	0.610		
X1	4.100		
X2	4.420		
Υ	1.270		
Y1	1.020		
Y2	3.810		
Y3	6.610		



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